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ENCLOSURES:

- (Application Patent)
(Specification 70 pages)
(Claims 7 pages)
(Abstract 1 page(s))
(Drawing Sheets no. 24 (F) (INF) _____)
(Transmittal Letter : New Divisional Apln.
(Check \$ 750.00 No: 14074)
(Declaration/Oath
(Assignment and Cover Sheet
(Information Disclosure Statement
(Response/Amendment - Preliminary A
(Extension of Time (In Duplicate)
(Small Entity Status
(Copy of Priority Document
(Appointment of Associate Attorneys
(_____)

RE: APPLICATION ATTY/SEC: MJM/cn
File no: 0553-0166.01

Applicant: Shunpei YAMAZAKI et al.

S.N.: Not Assigned Filing Date: Herewith

Title: Wiring Material and a Semiconductor Device Having a Wiring Using the Material, and the Manufacturing Method Thereof

Due date: _____ Date Sent: 7/29/2003

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

In Re Application of)
Yamazaki et al.)
Serial No.:) "Express Mail" Mailing Label No. EV 321709204
Filed: Herewith) Date of Deposit July 29, 2003
For: Wiring Material And A) I hereby certify that this correspondence is being
Semiconductor Device Having A) deposited with the United States Postal Service
Wiring Using the Material, And The) "Express Mail Post Office to Addressee" service
Manufacturing Method Thereof) under 37 CFR1.10 on the date indicated above
Art Unit:) and is addressed to: Commissioner for Patents,
Examiner:) P.O. Box 1450, Alexandria, VA 22313-1450
Name: yue x luan
(typed or printed)
Signature yue x luan

Commissioner for Patents
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Alexandria, VA 22313-1450

PRELIMINARY AMENDMENT A

Sir:

Prior to examination and calculation of the fees, please amend the above-identified application as follows:

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